L Number	Hits	Search Text	DB	Time stamp
1	112	(((dielectric insulat\$3) and (hydrogen H2	USPAT;	2004/09/29 18:19
	_	"H.sub.2")) and (wet near10 (treat\$3	US-PGPUB	
		solution))) and ((dielectric insulat\$3)		
		near100 (hydrogen H2 "H.sub.2") near100 (wet	1	
		near10 (treat\$3 solution)))		
2	40		USPAT;	2004/09/29 18:19
_		"H.sub.2")) and (wet near10 (treat\$3	US-PGPUB	2001,03,23 10:23
		solution))) and ((dielectric insulat\$3)	55 15155	
		near100 (hydrogen H2 "H.sub.2") near100 (wet	1	
		near10 (treat\$3 solution)))) and (argon Ar)	1	
3	10	(((dielectric insulat\$3) and (hydrogen H2	EPO; JPO;	2004/09/29 18:19
	10	"H.sub.2")) and (wet near10 (treat\$3	DERWENT;	2004,00,20 10.19
		solution))) and ((dielectric insulat\$3)	IBM TDB	İ
		near100 (hydrogen H2 "H.sub.2") near100 (wet	1557-106	
		near100 (hydrogen Hz "H.Sub.2") hear100 (wet near10 (treat\$3 solution)))	1	
5	0		EDO. TRO	2004/09/20 19:10
	U	"H.sub.2")) and (wet near10 (treat\$3	EPO; JPO;	2004/09/29 18:19
			DERWENT;	
		solution))) and ((dielectric insulat\$3)	IBM_TDB	
		near100 (hydrogen H2 "H.sub.2") near100 (wet	1	
6	10070	near10 (treat\$3 solution))) and (argon Ar)	HODAG	2004/00/00 30 30
٥	10279	(ILD (inter near5 dielectric) IMD)	USPAT;	2004/09/29 18:39
-	2216	(/TID /inhow noows dialaterial TMD))	US-PGPUB	0004/00/00 70 75
7	3316	((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:39
	005	(hydrogen "H.sub.2")	US-PGPUB	0004/00/00 50 55
8	2351	(((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:39
	4 4 4 4	(hydrogen "H.sub.2")) and (wet solution)	US-PGPUB	0004/00/55 55 55
9	1440	((((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:21
		(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	
1.0	<b>^</b>	and (clean\$3 treat\$3)		
10	942	(((((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:21
		(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	
		and (clean\$3 treat\$3)) and plasma		
11	523	((((((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:22
		(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	
		and (clean\$3 treat\$3)) and plasma) and		
1.0		(argon "Ar")		
12	332	1	USPAT;	2004/09/29 18:22
		and (hydrogen "H.sub.2")) and (wet	US-PGPUB	
		solution)) and (clean\$3 treat\$3)) and	İ	
,		plasma) and (argon "Ar")) and (resist PR		
		photoresist)		
13	327	((((((((ILD (inter near5 dielectric) IMD))	USPAT;	2004/09/29 18:23
		and (hydrogen "H.sub.2")) and (wet	US-PGPUB	
		solution)) and (clean\$3 treat\$3)) and		
		plasma) and (argon "Ar")) and (resist PR		
		photoresist)) and (etch\$3 pattern\$3)		
14	2414	(ILD (inter near5 dielectric) IMD)	EPO; JPO;	2004/09/29 18:39
			DERWENT;	
			IBM_TDB	
15	86	((ILD (inter near5 dielectric) IMD)) and	EPO; JPO;	2004/09/29 18:39
		(hydrogen "H.sub.2")	DERWENT;	
			IBM_TDB	
16	14	(((ILD (inter near5 dielectric) IMD)) and	EPO; JPO;	2004/09/29 18:40
		(hydrogen "H.sub.2")) and (wet solution)	DERWENT;	
			IBM TDB	
				L